



*SPW*  
PATENT  
8038-1011-2

IN THE U.S. PATENT AND TRADEMARK OFFICE

In re application of

Koichi OHTO Conf. 4540

Application No. 10/622,645 Group 2813

Filed July 21, 2003 Examiner E. Kielin

METHOD FOR FORMING A CAPPING LAYER  
ON A COPPER INTERCONNECT

**SUPPLEMENTAL AMENDMENT**

Assistant Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

April 14, 2005

Sir:

Supplemental to the response filed on April 6, 2005,  
please further amend the above-identified application as follows:

**Amendments to the Claims** are reflected in the listing  
of claims which begins on page 2 of this paper.

**Remarks** begin on page 4 of this paper.